

In the claims:

Please amend the claims as follows:

Cl
1. (Currently Amended) A semiconductor device comprising:
a supporting substrate made of insulating material;
a conductive pattern provided on a surface of the supporting substrate;
an external connecting terminal provided on a back surface of the supporting substrate
and electrically connected to the conductive pattern through the substrate;
a circuit element provided on the conductive pattern;
a glass plate that covers the circuit element and that forms a hollow airtight portion
between the supporting substrate and the glass plate; and
a light-shielding adhesive resin applied over an entire surface of the glass plate.

2. (Previously Canceled)

3. (Original) A semiconductor device according to claim 1, wherein the circuit element
includes a semiconductor element or a fuse element.

4-7. (Previously Withdrawn)

8. (Previously Added) A semiconductor device comprising:
a substrate;
a circuit member provided on the substrate;
a terminal provided on a back of the substrate and electrically connected to the circuit
member through the substrate;
a wall surrounding the circuit member; and
a transparent plate with a light-shielding adhesive resin provided over the transparent
plate's entire surface, said transparent plate adhered on the wall and over the circuit member to
form an airtight cavity between the substrate and the transparent plate.

C/ 9. (Previously Added) The semiconductor device according to claim 8 wherein the circuit member comprises:

a conductive pattern disposed over the substrate; and
a semiconductor chip disposed over the conductive pattern.

10. (Previously Added) The semiconductor device according to claim 8 wherein the substrate comprises insulating material.

11. (Previously Added) The semiconductor device according to claim 8, wherein the circuit member includes a fuse element.

12. (New) The semiconductor device according to claim 1, wherein said external connecting terminal is electrically connected to the conductive pattern through the substrate by a via hole.

13. (New) The semiconductor device according to claim 8, wherein said terminal is electrically connected to the conductive pattern through the substrate by a via hole.
